

Reduction of Near Field Electro-Magnetic Scattering Using High Impedance Metallization Terminations

Abstract

The present invention uses metallization termination techniques to reduce the electro-magnetic field scattering at the edges of metallized areas. The metallization termination techniques provide a gradual transition from high conductivity areas to high impedance areas. The mobile phone antenna illuminates the PCB allowing currents to flow on the PCB. When the currents reach edges of the PCB they flow through a region of increasingly high impedance without reflecting back or scattering.